Integrated Circuit Systems, Inc.

ICS8545I

LOW SKEW, 1-TO-4 LVCMOS/LVTTL-TO-LVDS FANOUT BUFFER

GENERAL DESCRIPTION

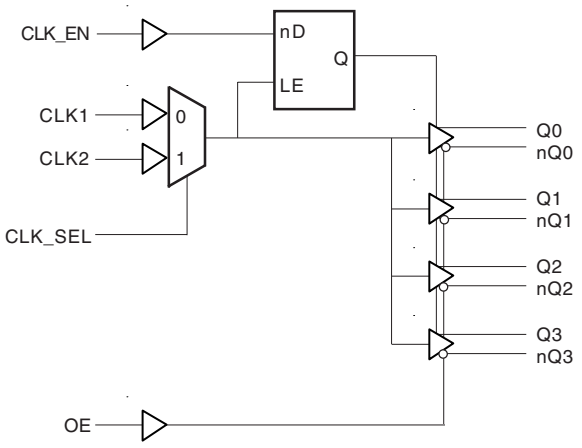
The ICS8545I is a low skew, high performance 1-to-4 LVCMOS/LVTTL-to-LVDS clock fanout buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. Utilizing Low Voltage Differential Signaling (LVDS) the ICS8545I provides a low power, low noise, solution for distributing clock signals over controlled impedances of 100Ω. The ICS8545I accepts a LVCMOS input level and translates it to 3.3V LVDS output levels.

Guaranteed output and part-to-part skew characteristics make the ICS8545I ideal for those applications demanding well defined performance and repeatability.

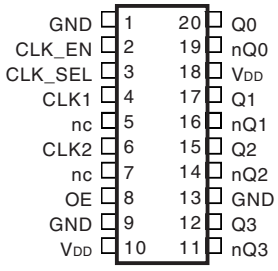
FEATURES

- 4 LVDS outputs
- 2 selectableLVCMOS/LVTTL clock inputs to support redundant or selectable frequency fanout applications
- CLK1 and CLK2 can accept the following input levels: LVCMOS or LVTTL
- Maximum output frequency: 650MHz
- Translates LVCMOS/LVTTL input signals to LVDS levels
- Output skew: 40ps (maximum)
- Part-to-part skew: 500ps (maximum)
- Propagation delay: 3.6ns (maximum)
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature

BLOCK DIAGRAM



PIN ASSIGNMENT



ICS8545I

20-Lead TSSOP
6.5mm x 4.4mm x 0.92mm body package
G Package
Top View

TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 9, 13	GND	Power		Power supply ground.
2	CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follows clock input. When LOW, Q outputs are forced low, nQ outputs are forced high. LVCMOS / LVTTL interface levels.
3	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK2 input. When LOW, selects CLK1 input. LVCMOS / LVTTL interface levels.
4	CLK1	Input	Pulldown	LVCMOS / LVTTL clock input.
5, 7	nc	Unused		Unused pins.
6	CLK2	Input	Pulldown	LVCMOS / LVTTL clock input.
8	OE	Input	Pullup	Output enable. Controls enabling and disabling of outputs Q0, nQ0 thru Q3, nQ3. LVCMOS / LVTTL interface levels.
10, 18	V_{DD}	Power		Positive supply pins.
11, 12	nQ3, Q3	Output		Differential output pair. LVDS interface levels.
14, 15	nQ2, Q2	Output		Differential output pair. LVDS interface levels.
16, 17	nQ1, Q1	Output		Differential output pair. LVDS interface levels.
19, 20	nQ0, Q0	Output		Differential output pair. LVDS interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
R_{PULLUP}	Input Pullup Resistor			51		KΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		KΩ

TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs				Outputs	
OE	**CLK_EN**	**CLK_SEL**	**Selected Source**	**Q0:Q3**	**nQ0:nQ3**
0	X	X		Hi Z	Hi Z
1	0	0	CLK1	Low	High
1	0	1	CLK2	Low	High
1	1	0	CLK1	ACTIVE	ACTIVE
1	1	1	CLK2	ACTIVE	ACTIVE

After CLK_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1.
In the active mode, the state of the outputs are a function of the CLK1 and CLK2 inputs as described in Table 3B.

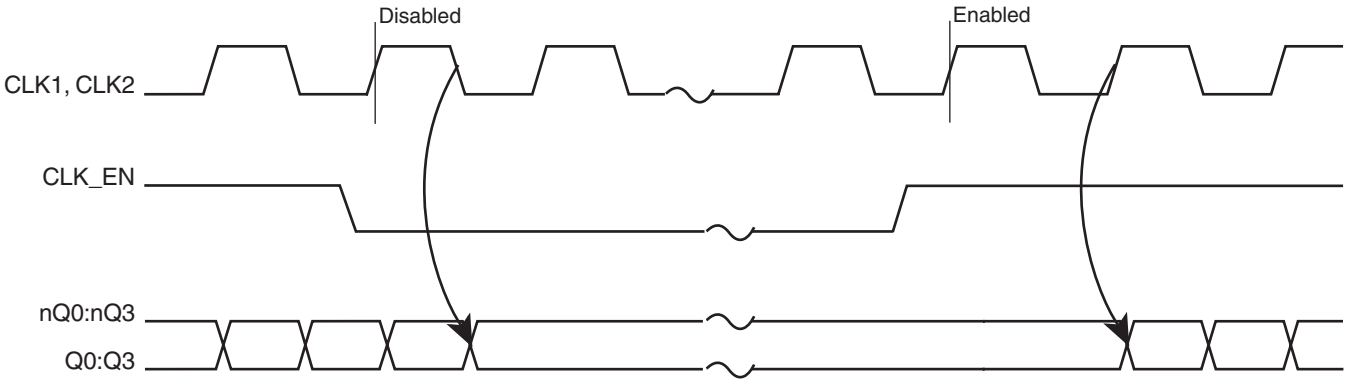


FIGURE 1. CLK_EN TIMING DIAGRAM

TABLE 3B. CLOCK INPUT FUNCTION TABLE

Inputs	Outputs	
CLK1 or CLK 2	**Q0:Q3**	**nQ0:nQ3**
0	LOW	HIGH
1	HIGH	LOW

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{DD}	4.6V
Inputs, V_I	-0.5V to V_{DD} + 0.5V
Outputs, I_O	
Continuous Current	10mA
Surge Current	15mA
Package Thermal Impedance, θ_{JA}	73.2°C/W (0 lfpm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, V_{DD} = 3.3V±5%, TA = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Positive Supply Voltage		3.135	3.3	3.465	V
I_{DD}	Power Supply Current				52	mA

TABLE 4B. LVCMOS / LVTTL DC CHARACTERISTICS, V_{DD} = 3.3V±5%, TA = -40°C TO 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	CLK1, CLK2		2		V_{DD} + 0.3	V
		CLK_EN, CLK_SEL, OE		2		V_{DD} + 0.3	V
V_{IL}	Input Low Voltage	CLK1, CLK2		-0.3		1.3	V
		CLK_EN, CLK_SEL, OE		-0.3		0.8	V
I_{IH}	Input High Current	CLK1, CLK2, CLK_SEL	V_{DD} = V_{IN} = 3.465V			150	µA
		CLK_EN, OE	V_{DD} = V_{IN} = 3.465V			5	µA
I_{IL}	Input Low Current	CLK1, CLK2, CLK_SEL	V_{DD} = 3.465V, V_{IN} = 0V	-5			µA
		CLK_EN, OE	V_{DD} = 3.465V, V_{IN} = 0V	-150			µA

NOTE: Outputs terminated with 50Ω to V_{DD}/2. See Parameter Measurement Information, "Output Load Test Circuit".

TABLE 4C. LVDS DC CHARACTERISTICS, V_{DD} = 3.3V±5%, TA = -40°C TO 85°C

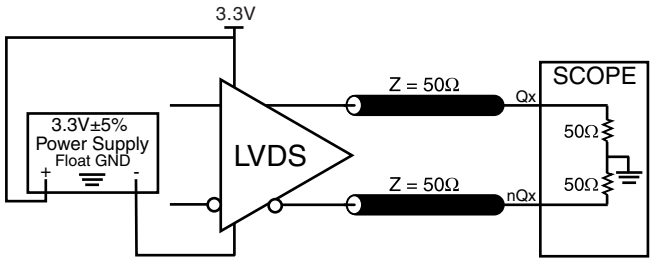
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OD}	Differential Output Voltage		200	280	360	mV
ΔV_{OD}	V_{OD} Magnitude Change				40	mV
V_{OS}	Offset Voltage		1.125	1.25	1.375	V
ΔV_{OS}	V_{OS} Magnitude Change			5	25	mV
I_{OZ}	High Impedance Leakage Current		-10	±1	+10	µA
I_{OFF}	Power Off Leakage		-20	±1	+20	µA
I_{OSD}	Differential Output Short Circuit Current			-3.5	-5	mA
I_{OS}	Output Short Circuit Current			-3.5	-5	mA
V_{OH}	Output Voltage High			1.34	1.6	V
V_{OL}	Output Voltage Low		0.9	1.06		V

TABLE 5. AC CHARACTERISTICS, V_{DD} = 3.3V±5%, T_A = -40°C TO 85°C

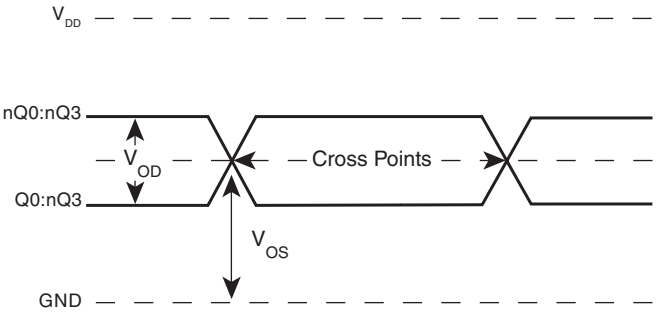
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				650	MHz
t_{PD}	Propagation Delay; NOTE 1	f ≤ 650MHz	1.4		3.6	ns
*t*sk(o)	Output Skew; NOTE 2, 4				40	ps
*t*sk(pp)	Part-to-Part Skew; NOTE 3, 4				500	ps
t_R / t_F	Output Rise/Fall Time	20% to 80% @ f ≤ 266MHz	200		700	ps
odc	Output Duty Cycle	f ≤ 266MHz	45		55	%
		f > 266MHz	40		60	%

All parameters measured at f ≤ 650MHz unless noted otherwise.
NOTE 1: Measured from the V_{DD}/2 of the input to the differential output crossing point.
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V_{DD}/2 of the input to the differential output crossing point.
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

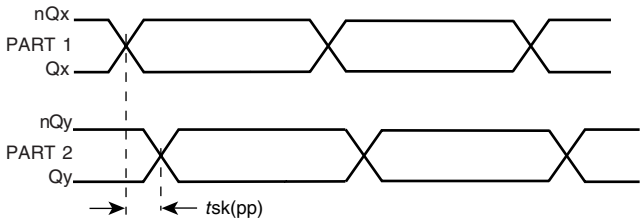
PARAMETER MEASUREMENT INFORMATION



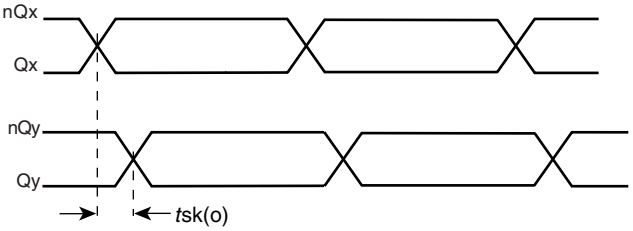
3.3V OUTPUT LOAD AC TEST CIRCUIT



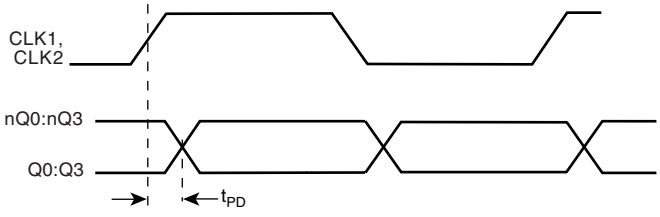
DIFFERENTIAL OUTPUT LEVEL



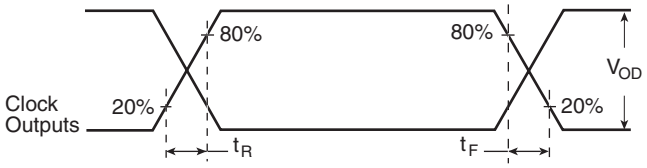
PART-TO-PART SKEW



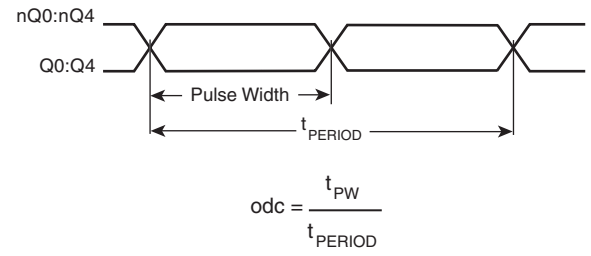
OUTPUT SKEW



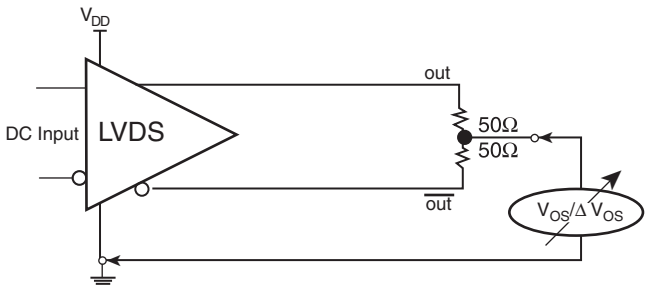
PROPAGATION DELAY



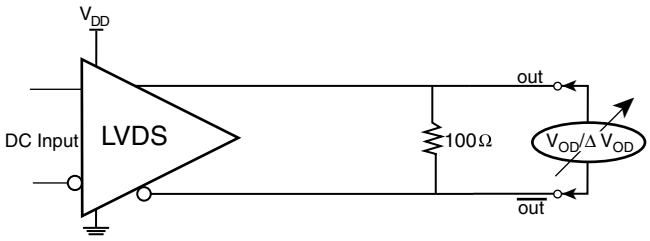
OUTPUT RISE/FALL TIME



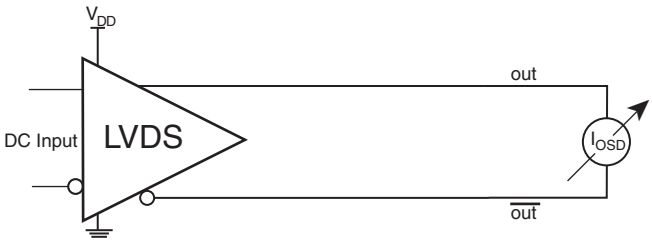
OUTPUT DUTY CYCLE/PULSE WIDTH PERIOD



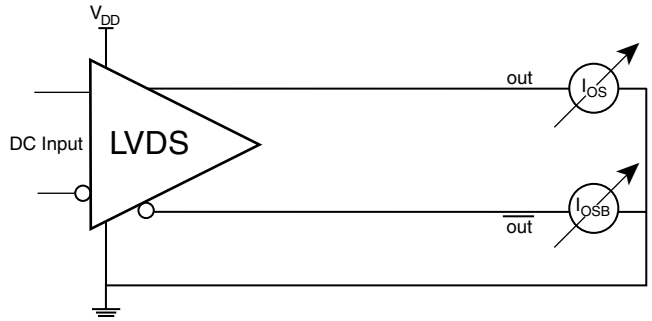
OFFSET VOLTAGE



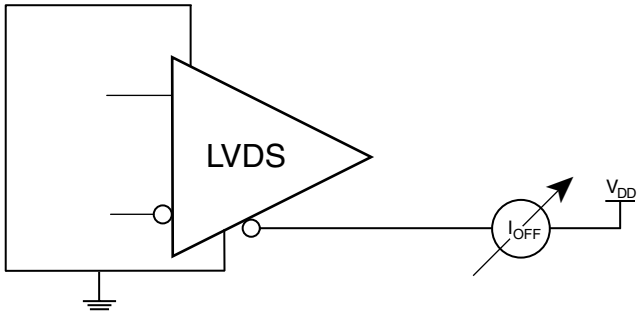
DIFFERENTIAL OUTPUT VOLTAGE



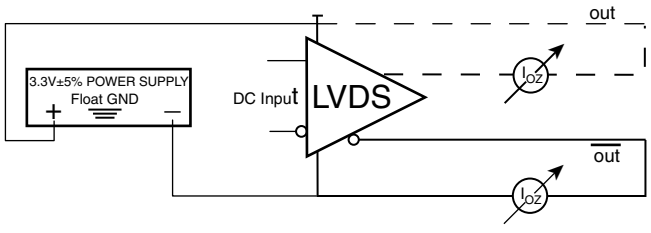
DIFFERENTIAL OUTPUT SHORT CIRCUIT CURRENT



OUTPUT SHORT CIRCUIT CURRENT



POWER OFF LEAKAGE



HIGH IMPEDANCE LEAKAGE CURRENT

PARAMETER MEASUREMENT INFORMATION

3.3V LVDS DRIVER TERMINATION

A general LVDS interface is shown in *Figure 2*. In a 100Ω differential transmission line environment, LVDS drivers require a matched load termination of 100Ω across near the receiver input. For a multiple LVDS outputs buffer, if only partial outputs are used, it is recommended to terminate the un-used outputs.

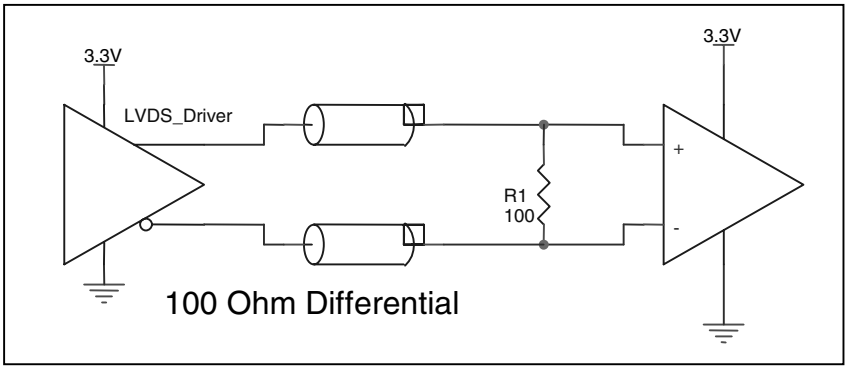


FIGURE 2. TYPICAL LVDS DRIVER TERMINATION

SCHEMATIC EXAMPLE

Figure 3 shows a schematic example of the ICS8545I. In this example, the CLKx input is selected. The decoupling capacitors should be physically located near the power pin. For ICS8545I, the unused clock outputs can be left floating.

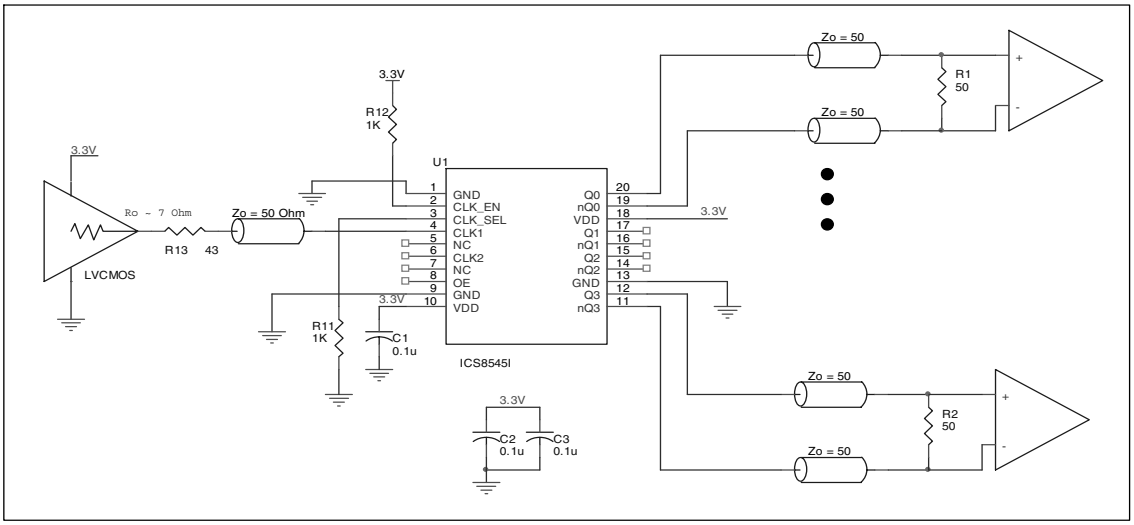


FIGURE 3. ICS8545I LVDS BUFFER SCHEMATIC EXAMPLE

RELIABILITY INFORMATION

TABLE 6. θ_{JA} VS. AIR FLOW TABLE FOR 20 LEAD TSSOP

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	**200**	**500**
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS8545I is: 644

PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

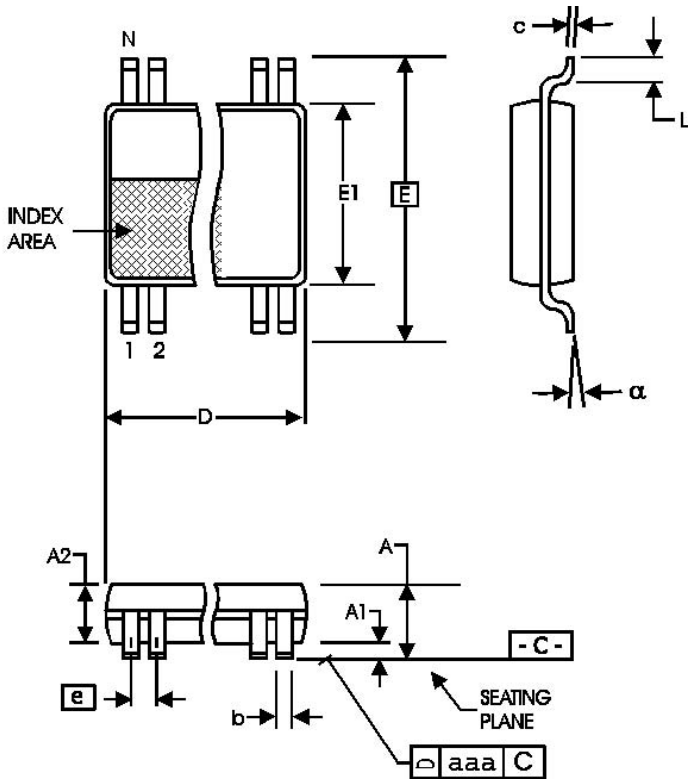


TABLE 7. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MIN	MAX
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153

TABLE 8. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS8545BGI	ICS8545BGI	20 lead TSSOP	72 per tube	-40°C to 85°C
ICS8545BGIT	ICS8545BGI	20 lead TSSOP on Tape and Reel	2500	-40°C to 85°C